

#### -30V P+P-Channel Enhancement Mode MOSFET

#### Description

The AP4953A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = -30V I<sub>D</sub> =-7A

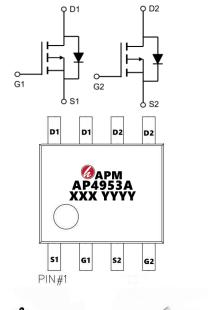
 $R_{DS(ON)} < 48m\Omega @ V_{GS}=10V$  (Type: 37m $\Omega$ )

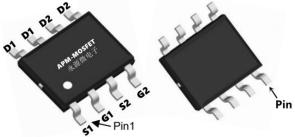
#### Application

Lithium battery protection

Wireless impact

Mobile phone fast charging





#### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)	
AP4953A	SOP-8	AP4953A XXX YYYY	3000	
bsolute Maxim	um Ratings (T <sub>A</sub> =25°C unless otherwise n	oted)		
Symbol	Parameter	Rating	Units	
Vds	Drain-Source Voltage	-30	V	
Vgs	Gate-Source Voltage	±20	V	
ID@TA=25°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-7	А	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-4.3	А	
ldм	Pulsed Drain Current <sup>2</sup>	-21	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	81.2	mJ	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	1.5	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	85	°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	25	°C/W	



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Symbol	Parameter	Conditions	Min	Тур	Max	Units	
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250µA	-30	-33	-	V	
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1	μA	
IGSS	Gate-Source Leakage	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA	
VGS(th)	Gate-Source Threshold Voltage <sup>3</sup>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250µA	-1	-1.6	-2.5	V	
RDS(on)	Drain-Source on-State Resistance <sup>3</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.1A	-	37	48	mΩ	
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.0A	-	58	65		
Ciss	Input Capacitance		-	530	-	pF	
Coss	Output Capacitance	V <sub>GS</sub> = 0V , V <sub>DS</sub> = -15V, f= 1.0MHz	-	70	-		
Crss	Reverse Transfer Capacitance		-	56	-		
td(on)	Turn-on Delay Time <sup>4</sup>		-	14	-		
tr	Rise Time <sup>4</sup>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V ,	-	61	-	- 0	
td(off)	Turn-off Delay Time⁴	R <sub>L</sub> = 15Ω,R <sub>GEN</sub> = 2.5Ω	-	19	-	nS	
tf	Fall Time <sup>4</sup>		-	10	-		
Qg	Total Gate Charge <sup>4</sup>		-	6.8	-		
Qgs	Gate-Source Charge <sup>4</sup>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V, I <sub>D</sub> = -4.1A	-	1.0	-	nC	
Qgd	Gate-Drain Charge <sup>4</sup>		-	1.4	-		
VSD	Diode Forward Voltage	I <sub>S</sub> = -4.1A, V <sub>GS</sub> = 0V	-	-	-1.2	V	

#### Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Note :

 $1_{\mbox{\tiny V}}$  The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

 $2\,{\smallsetminus}\,$  The data tested by pulsed , pulse width  ${\leq}\,300\text{us}$  , duty cycle  ${\leq}\,2\%$ 

3、The power dissipation is limited by 150°C junction temperature

4. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

N



# **AP4953A**

3

4

15

Ciss

Coss

Crss

20

ω

ID= -4.1A

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#### **Typical Characteristics** 20 10 Vgs = -10V Vos= -5V Vgs = -3.5\ 8 16 Drain current -lo (A) -4.5V Drain current -lp (A) VGS $V_{GS} = -4V$ 12 6 Vgs = -3V 8 4 2 4 0 0 1 2 3 4 Drain-source voltage -V<sub>DS</sub> (V) 0 0 1 2 1 4 5 Gate-source voltage -V<sub>GS</sub> (V) Figure 2. Transfer Characteristics **Figure 1. Output Characteristics** 100 200 170 $\begin{array}{ccc} \text{On-Resistance} & R_{\text{Ds} \ (\text{on})} \ (\text{m}\Omega) \\ \text{cs} & \text{b} & \text{cs} & \text{cs} \\ \text{cs} & \text{b} & \text{cs} & \text{cs} \end{array}$ On-Resistance R<sub>05 (on)</sub> (mΩ) 08 101 101 001 Vas= -4.5V Vgs= -10V 20 50 0 20 8 0 2 4 6 10 0 6 9 12 Gate-source voltage -V<sub>GS</sub> (V) 3 Drain current -ID (A) Figure 3. RDS(ON) vs. ID Figure 4. R DS(ON) vs. V GS 10000 10 8 Capacitance (pF) 00 00 0001 Source current -ls (A) 6 4 10 2 F=1.0MHz 0 1 0.0 4 8 12 16 Drain-source voltage -V<sub>DS</sub> (V) 0.2 0.4 0.6 0.8 1.0 1.2 0 Source-drain voltage -V<sub>SD</sub> (V)

Figure 5.IS vs. VSD

**Figure 6. Capacitance Characteristics** 



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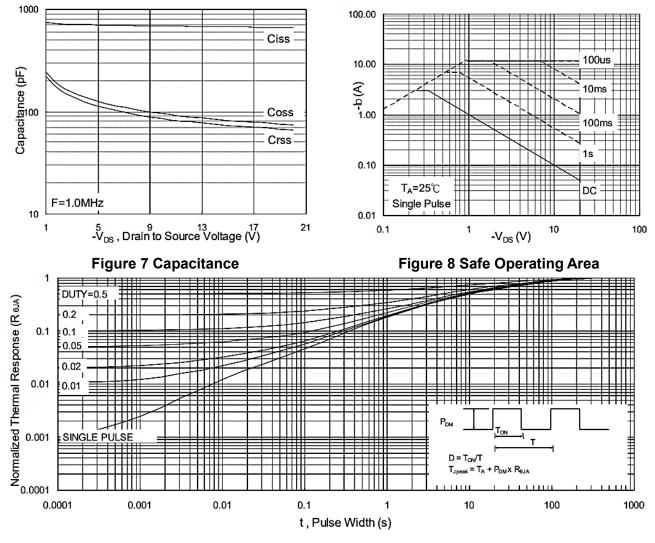


Figure 9 Normalized Maximum Transient Thermal Impedance

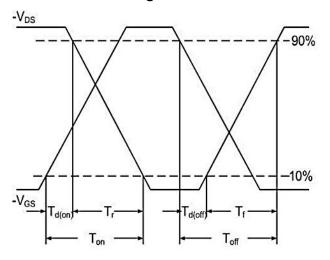
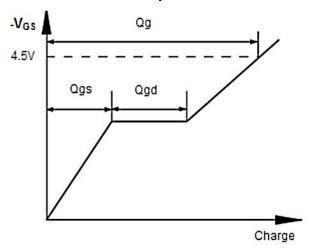


Figure 10 Switching Time Waveform

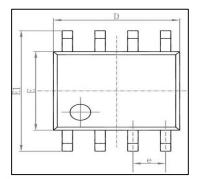


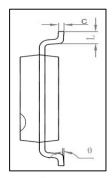


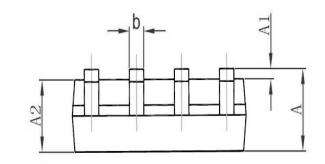


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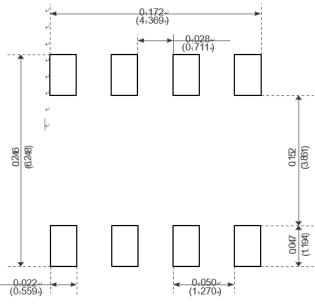
# Package Mechanical Data-SOP-8L







C	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
A	1.350	1. 750	0. 053	0.069
A1	0.100	0. 250	0.004	0. 010
A2	1.350	1.550	0. 053	0. 061
b	0. 330	0. 510	0.013	0. 020
с	0. 170	0. 250	0.006	0.010
D	4. 700	5. 100	0. 185	0. 200
E	3.800	4.000	0. 150	0. 157
E1	5.800	6. 200	0. 228	0. 244
е	1.270	(BSC)	0.050	(BSC)
L	0. 400	1.270	0.016	0.050
θ	<b>0</b> °	8 °	<b>0</b> °	8°



Recommended Minimum Pads



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Edition	Date	Change
Rve3.8	2020/1/31	Initial release
Rve3.9	2021/11/31	Reduce RDS

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AP4953A RVE:3.9

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